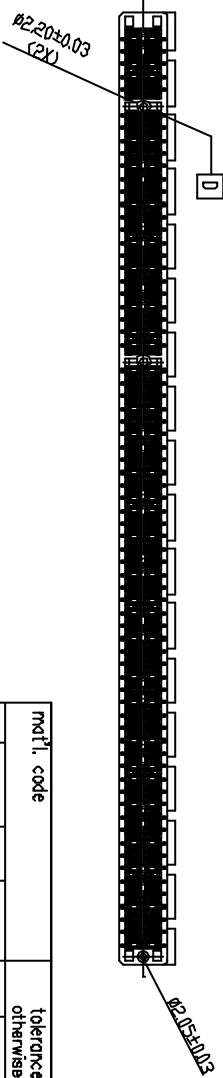
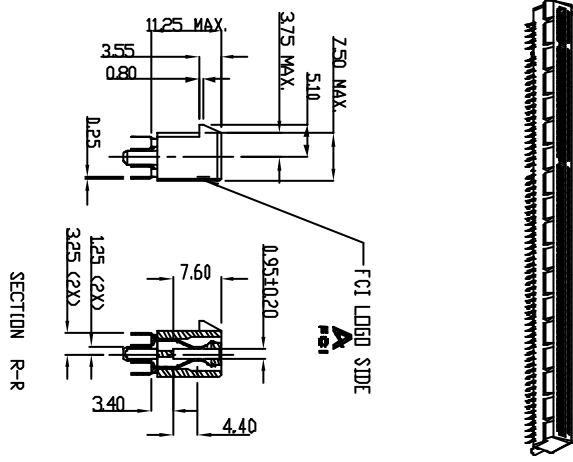
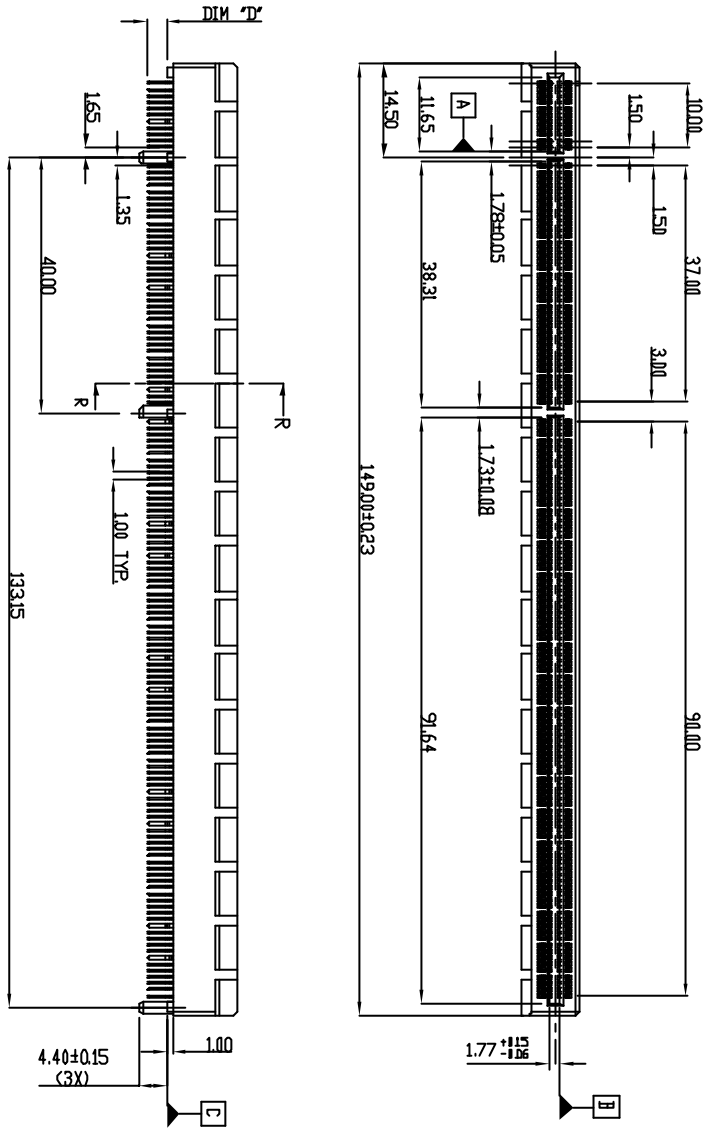


PROJ. NO.
SEE NOTE



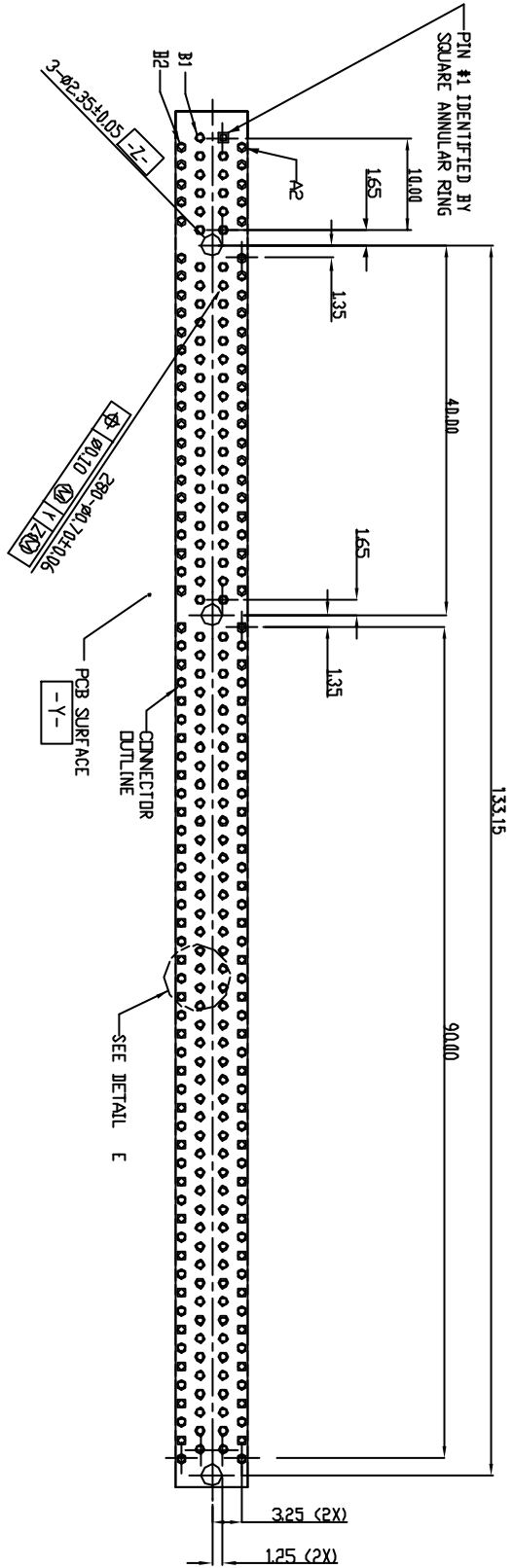
mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		FCI		www.fciconsult.com	
Ltr	eqn no	dr	date						
A	106-D240	J/H	10/22/05	linear	.X ±.38			PCI-E 280P CARD EDGE	
B	106-D013	J/H	1/18/06	angles	.XX ±.25	projection			
					.XXX ±.10				
					0° ±2°				
		dr	JASOEN HSU	10/22/05					
		enqr	JASOEN HSU	10/22/05					
		chr	STERLING LIN	10/22/05					
		appr	HC LIU	10/22/05					
sheet	revision								
index	sheet	1	2	3	4				

ACAD

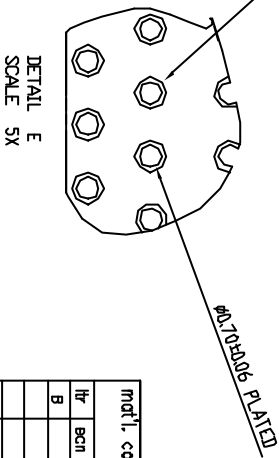
code code
22526

B

A



RECOMMENDED FOOTPRINT



mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		FCI		code	
lt	ben no	dr	date	linear	XX ±.25	projection	MM	product family	PCI
B				angular	° ±2°	scale	N/A	size dng no	10057596
				dr	JASON HSU	D/22/05		code	
				engr	JASON HSU	0/22/05		sheet	2 of 4
				chr	STERLING LN	0/22/05			
				ppxl	HC LDUU	0/22/05			
sheet	revision								
index	sheet								

ACAD

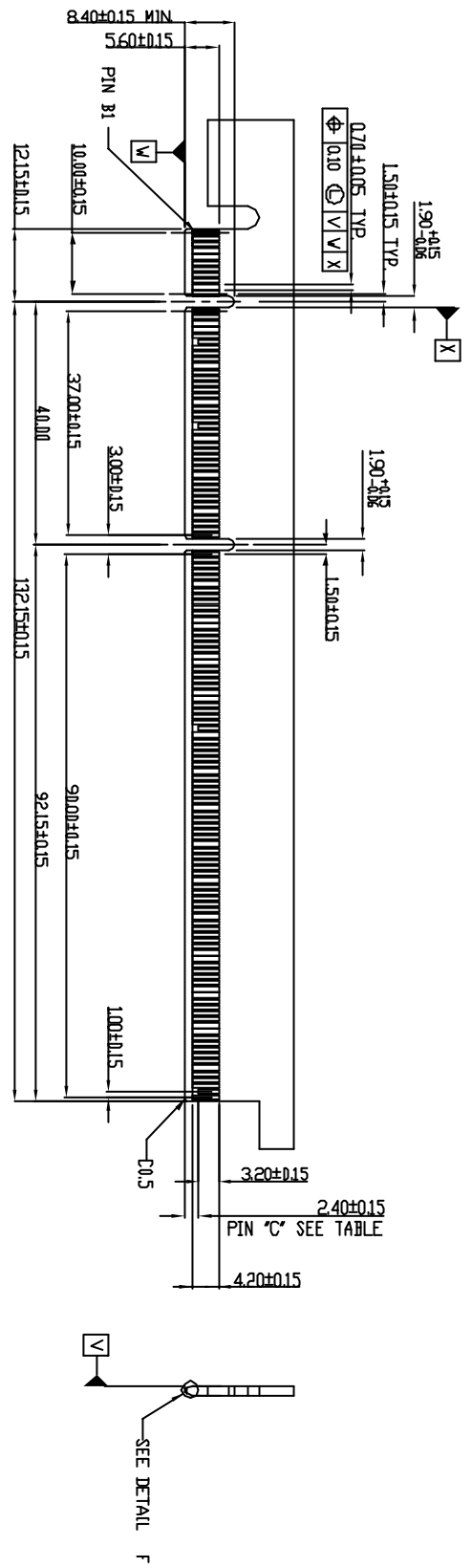
3

scope code 22526

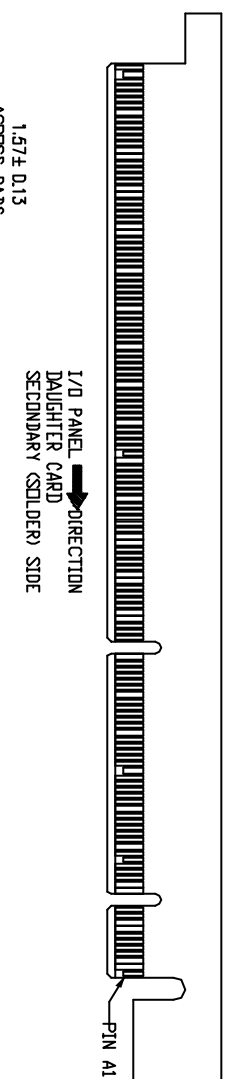
4

B

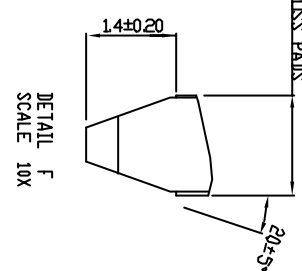
A



↑ 1/0 PANEL DIRECTION
PRIMARY (COMPONENT) SIDE



PIN °C	A1	A17	A31	A79	A139
	B17	B31	B79	B139	



mat'l. code	tolerances unless otherwise specified		CUSTOMER COPY			FCI www.fci.com www.fci.com
lfr	den no	dr	date			
B				.XX ±.25	°	PCI-E 280P CARD EDGE
				.XXX ±.10		
				OF ±.2		
				JASON HSU	10/22/05	
				JASON HSU	10/22/05	
				STERLING LIN	10/22/05	
				HC LKH	10/22/05	
sheet	revision					product family
index	sheet					PCI
						size dwg no
						10057596
						code
						sheet
						3 of 4

ACAD

1 | 2

3 |

code 22526

4

1 | 2

3 |

4



NOTES:
 1. MATERIAL: THERMOPLASTIC WITH GLASS FIBER, UL94V-0,
 HOUSING: COLOR IN BLACK,
 CONTACTS: COPPER ALLOY.
 2. FINISH:
 CONTACTS: GOLD PLATING ON CONTACT AREA,
 100 μM/MIN. TIN/LEAD OR MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDER TAILS,
 50 μM/MIN. NICKEL UNDERPLATING OVER ALL.
 3. DURABILITY: 50 CYCLES.

4. ROHS COMPATIBLE PRODUCT SPECIFICATIONS
 a. PLATING: 'LF' MEANS THE PRODUCT IS LEAD FREE, 25 μm min. MATTE PURE TIN OVER 1.27 μm MIN. NICKEL UNDERPLATE.
 b. MANUFACTURING PROCESS COMPATIBILITY: THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ± 5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM THICK CIRCUIT BOARD.
 PRODUCT NUMBER CODE
 10057596 - X X X X X X X X X X

HOUSING COLOR OPTIONS _____
 1-BLACK _____
 PEGS OPTIONS _____
 0-PLASTIC PEGS _____
 TERMINAL PLATING OPTIONS _____
 0-50 μM NI UNDERPLATE _____
 30 μM Au CONTACT AREA _____
 100 μM TIN TAIL AREA -----COMPATIBLE ROHS
 1-50 μM NI UNDERPLATE _____
 15 μM Au CONTACT AREA -----COMPATIBLE ROHS
 100 μM TIN TAIL AREA -----COMPATIBLE ROHS
 2-50 μM Ni UNDERPLATE _____
 GOLD FLASH CONTACT AREA _____
 100 μM TIN TAIL AREA -----COMPATIBLE ROHS

LEAD FREE
 PACKAGING OPTIONS
 1-TKAT PACKAGING
 RESERVE
 0

TAIL LENGTH OPTIONS		
DIN #	mm	SUGGESTED PCB THICKNESS
1	310	2.36±0.10
2	254	1.56±0.10

mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		 projection title PCI-E 280P CARD EDGE	
itr	ecm no	dr	date	indec	indec	scale	product family
B				.XX ±.25	.XXX ±.10	N/A	PCI
				angles	0° ±2°		PCI
				dr	JASON HSU 10/22/05		code
				engr	JASON HSU 0/22/05		sheet
				chr	STERLING LIN 10/22/05		4 of 4
				appr	HC LCU 10/22/05		
sheet	revision						
index	sheet						

ACAD

change code
22526